

	Type	Hits	Search Text
1	BRS	57	(438/\$.ccls. and substrate near5 (abrasing or abrasor or abraded or grinding)) and resin
2	BRS	33	(438/459.ccls.(abrasor or abraded)) and grinding and resin
3	BRS	2	((438/459.ccls.(abrasor or abraded)) and grinding and resin) and resin near5 (printed or spin-coating)
4	BRS	376	438/\$.ccls. and substrate near5 (abrasing or abrasor or abraded or grinding)
5	BRS	737	438/459.ccls.(abrasor or abraded)
6	BRS	0	438/\$.ccls. and packaging and substrate near5 abrasor
7	BRS	15	438/\$.ccls. and packaging and substrate near5 abras\$4
8	BRS	1	abraded and abrasor
9	BRS	156	((rough or uneven or harsh) adj surface) near (chip or die or wafer)
10	BRS	350	438/964
11	BRS	10	438/964.ccls. and rough\$4 near3 (chip or die or wafer)
12	BRS	26	438/112-127.ccls. and rough\$4 near3 (chip or die or wafer)
13	IS&R	2	("6184064").PN.
14	BRS	1	"5930603".PN.
15	BRS	96	438/112-127.ccls. and resin near5 print\$4
16	BRS	0	(438/112-127.ccls. and resin near5 print\$4) and (spin-coating)
17	BRS	0	(438/112-127.ccls. and resin near5 print\$4) and spin-coating

	DBs	Time Stamp	Comments	Error Definition
1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 15:45		
2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/17 18:20		
3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/17 18:12		
4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 17:39		
5	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/17 18:14		
6	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/17 18:21		
7	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/17 18:22		
8	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 15:59		
9	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 17:33		
10	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 17:33		
11	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 17:41		
12	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:27		
13	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 18:31		
14	USPAT	2002/01/24 18:32		
15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:29		
16	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:28		
17	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:28		

	Type	Hits	Search Text
18	BRS	96	438/112-127.ccls. and resin near5 (print\$4 or spin-coating)
19	BRS	57	438/112-127.ccls. and resin near3 (print\$4 or spin-coating)
20	BRS	0	438/112-127.ccls. and resin near3 spin-coating
21	BRS	1	438/112-127.ccls. and wafer near3 (print\$4 or spin-coat\$3) near3 resin
22	BRS	1	438/112-127.ccls. and wafer near5 (print\$4 or spin-coat\$3) near3 resin
23	BRS	1271	resin near5 (elastic adj modulus)
24	BRS	14	(resin near5 (elastic adj modulus)) and packaging and 257/\$
25	BRS	35	resin near5 (elastic adj modulus) and 257/\$
26	BRS	39	resin near5 (elastic adj modulus) and (N/m sub ((resin near5 (elastic adj modulus)) and N/m^2))
27	BRS	931	resin near5 (young adj modulus)
28	BRS	13	resin near5 (young adj modulus) and packaging and 257/\$
29	BRS	0	resin near5 (young adj modulus) and rubber and silicon and polyimide and uretahane
30	BRS	558	(rubber or silicon or polyimide or uretahane) near5 (young adj modulus)

	DBs	Time Stamp	Comments	Error Definition
18	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:30		
19	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 12:15		
20	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:37		
21	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:39		
22	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/24 19:39		
23	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 12:26		
24	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 12:18		Truncation Overflow. Return string from Server is: 5`233112`
25	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 12:23		Truncation Overflow. Return string from Server is: 5`1441252
26	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 13:07		
27	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 13:27		
28	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 13:08		Truncation Overflow. Return string from Server is: 5`1441252
29	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 13:29		
30	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 13:30		

	Type	Hits	Search Text
31	BRS	8	438/\$.ccls. and substrate near5 (abrasing or abrasor or abraded or grinding) and (mirror adj finish)
32	BRS	710	(mirror adj finish) and abra\$5
33	BRS	178	(mirror adj finish) with abra\$5
34	BRS	16	(mirror adj finish) with abra\$5 with substrate
35	BRS	1	(chip die IC) with wafer with resin and (mirror adj finish)
36	BRS	25	wafer with resin and (mirror adj finish)
37	BRS	19	(chip die IC) with wafer with resin and ((mirror adj finish) smoothing polish)
38	BRS	32	257/459.ccls.and ((mirror adj finish) smooth\$5 polish)
39	BRS	149	(flip adj chip) with wafer and resin
40	BRS	606	257/778.ccls. and resin
41	BRS	112	wafer near5 (epoxy adj resin)
42	BRS	8	wafer near5 (chip die) near5 (epoxy adj resin)
43	BRS	1	wafer near5 (epoxy adj resin) near5 (printed spin-coated)
44	BRS	142	(257/620.ccls. 438/113,458,462.ccls.) and (grind\$3 abras\$4) and (smooth\$3 polish\$3)
45	IS&R	2	("6136668").PN.
46	BRS	0	(protective adj tape) near2 (epoxy adj resin)

	DBs	Time Stamp	Comments	Error Definition
31	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 17:42		
32	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 17:43		
33	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 17:44		
34	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 18:08		
35	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 18:15		
36	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 18:12		
37	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 18:19		
38	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 19:07		
39	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 19:16		
40	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 20:23		
41	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 20:24		
42	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/18 20:25		
43	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/19 10:59		
44	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/19 11:53		
45	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/19 11:18		
46	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/19 11:54		

	Type	Hits	Search Text
47	BRS	1	(protective adj tape) near5 (epoxy adj resin)
48	BRS	30	(protective adj tape) and (epoxy adj resin)

	DBs	Time Stamp	Comments	Error Definition
47	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/19 11:54		
48	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/07/19 13:14		